

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current	IPP	1.5	А	8/20µs (Note 7)
ESD Protection – Contact Discharge	V _{ESD_Contact}	±15	kV	Standard IEC 61000-4-2
ESD Protection – Air Discharge	V _{ESD_Air}	±15	kV	Standard IEC 61000-4-2

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	PD	300	mW
Thermal Resistance, Junction to Ambient $T_A = +25^{\circ}C$	R _{θJA}	417	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Standoff Voltage	V _{RWM}	-	—	5.5	V	—
Channel Leakage Current (Note 6)	I _R	-	—	100	nA	$V_R = 5V$, Any I/O to GND
Reverse breakdown voltage	V _{BR}	6.0	—	-	V	I _R = 1mA
Clamping Voltage, Positive Transients (Note 7)	Vc	-	10	12	V	$I_{PP} = 1A, t_p = 8/20\mu s$
Channel Innut Canaditanea (Note 9)	CT	-	0.5	-	рF	$V_R = 0V$, f = 1MHz, Any I/O to GND
Channel Input Capacitance (Note 8)		_	0.4	0.65		V_R = 2.5V, f = 1MHz, Any I/O to GND
Dynamic Resistance	R _{DYN}	_	0.9	_	Ω	I _{PP} = 1A, t _p = 8/20µs

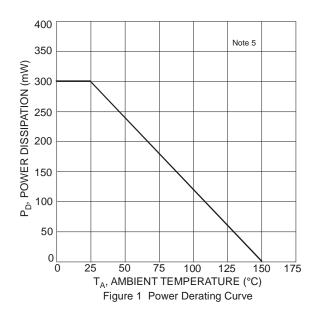
Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.

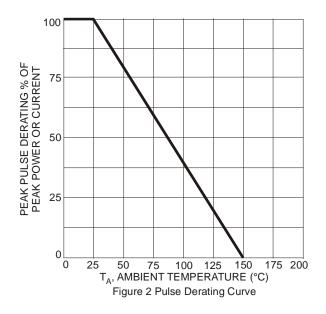
6. Short duration pulse test used to minimize self-heating effect.

7. Clamping voltage value is based on an 8x20µs peak pulse current (Ipp) waveform.

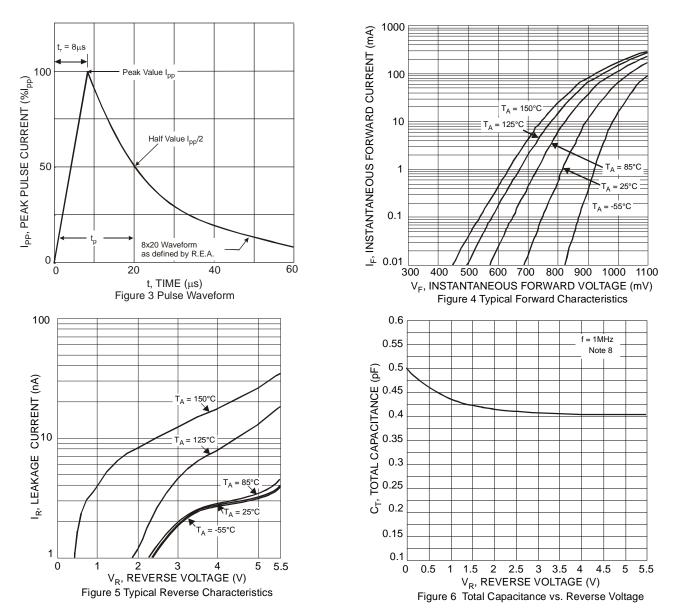
8. Measured from any I/O to GND.

9. For information on the impact of Diodes' USB 2.0 compatible ESD protectors on signal integrity including eye diagram plots, please refer to AN77 at the following URL: http://www.diodes.com/destools/appnote_dnote.html.



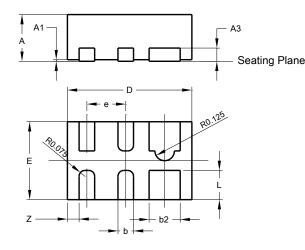






Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

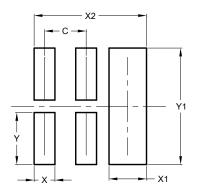


U-DFN1610-6					
Dim	Min	Max	Тур		
Α	0.545	0.605	0.575		
A1	0.00	0.05	0.03		
A3	-	-	0.13		
b	0.15	0.25	0.20		
b2	0.35	0.45	0.40		
D	1.550	1.675	1.600		
Е	0.950	1.075	1.000		
е	0.50 BSC				
L	0.325	0.425	0.375		
z	-	-	0.150		
All	All Dimensions in mm				



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value	
Dimensions	(in mm)	
С	0.500	
Х	0.250	
X1	0.450	
X2	1.350	
Y	0.625	
Y1	1.400	

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